



SOT1571-7

plastic, thermal enhanced low profile quad flat package; 48 leads; 0.5 mm pitch, 7 mm x 7 mm x 1.4 mm body

14 December 2017

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HLQFP48
Package style descriptive code	HLQFP (thermal enhanced low profile quad flat package)
Package body material type	P (plastic)
JEDEC package outline code	MS-026 BBC
Mounting method type	S (surface mount)
Issue date	28-8-2017
Manufacturer package code	98ASA01111D

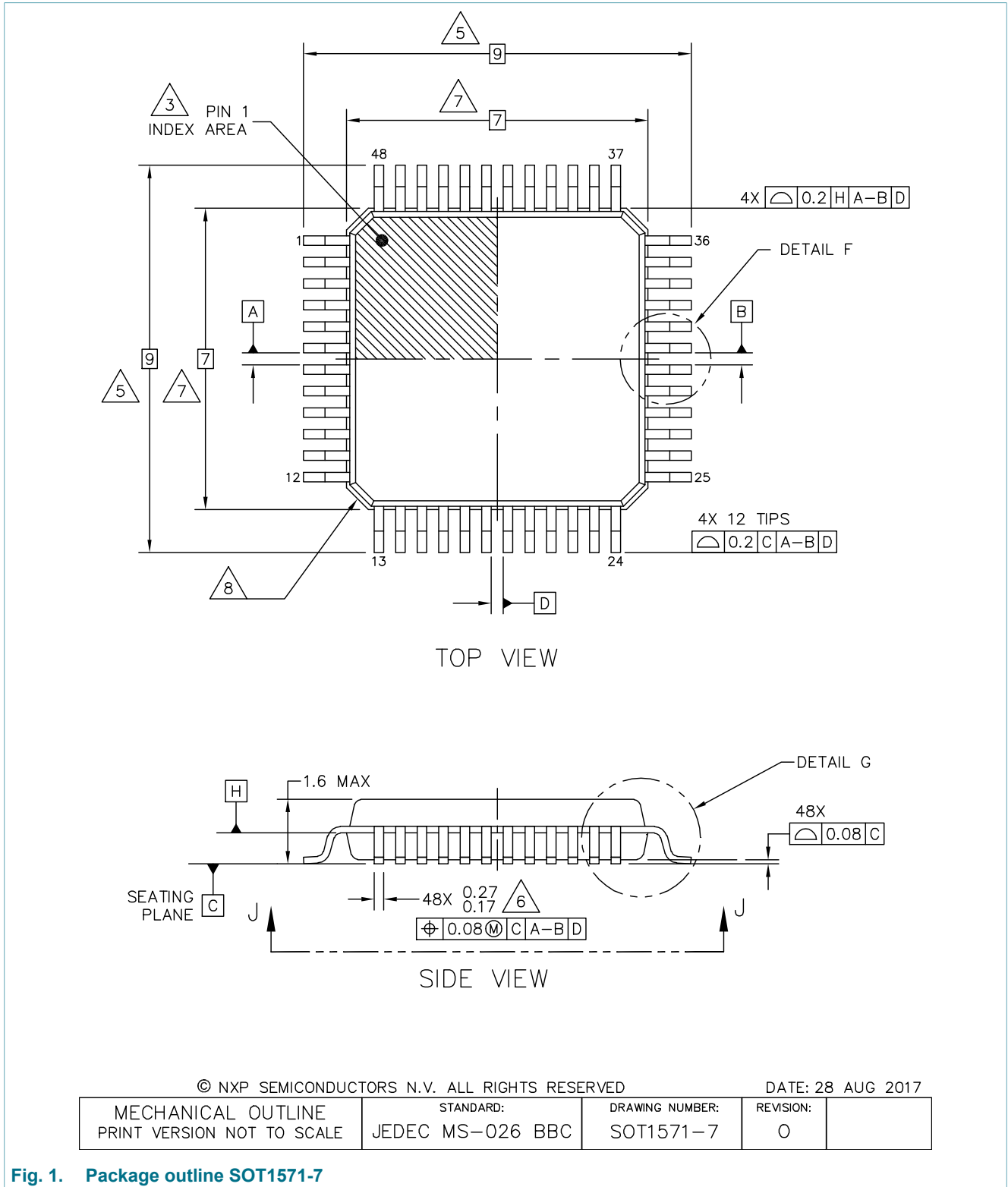
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	7	-	mm
E	package width	-	-	7	-	mm
A ₂	package height	-	-	1.4	-	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	48	-	A/A



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2. Package outline



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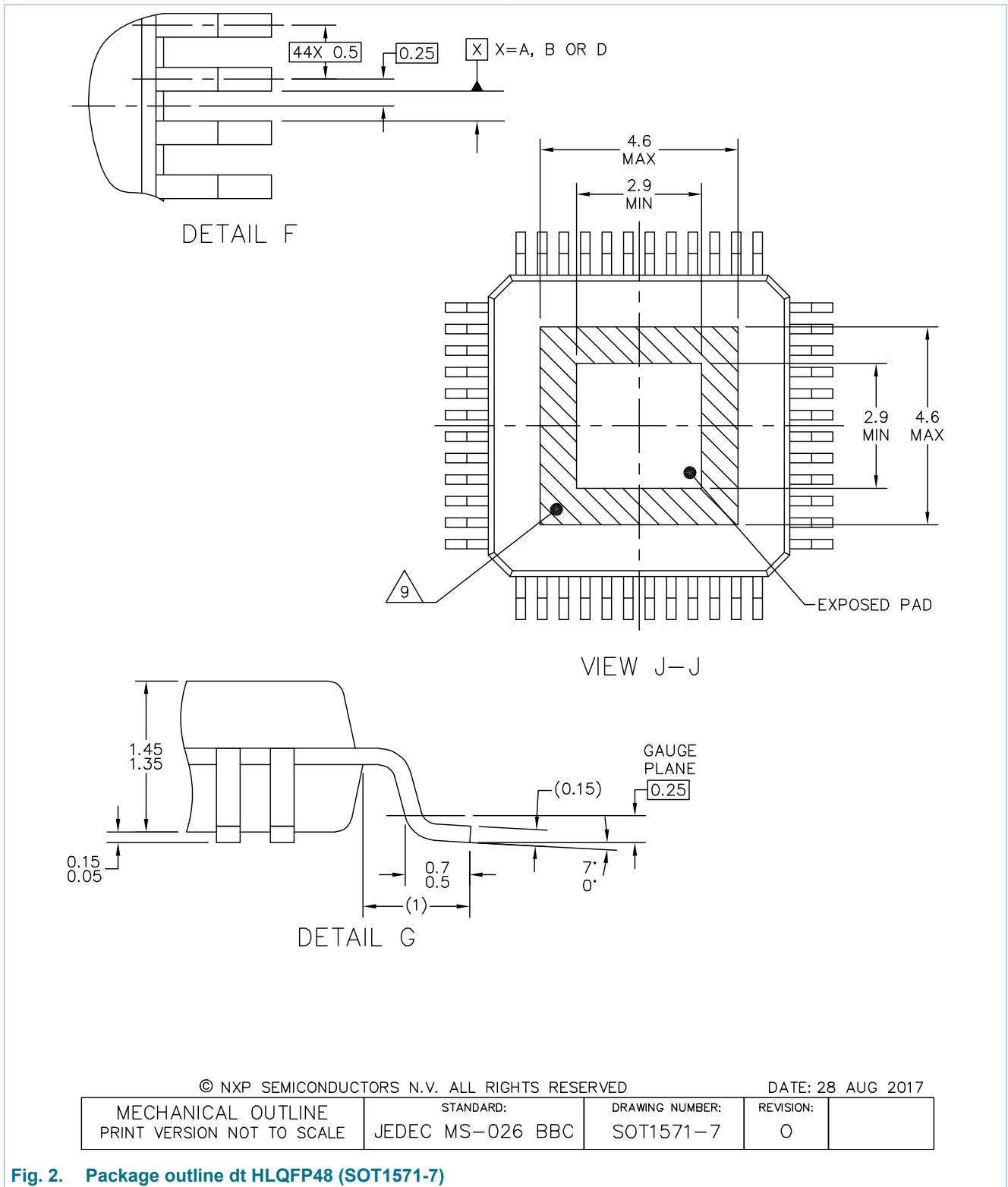


Fig. 2. Package outline dt HLQFP48 (SOT1571-7)

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NOTES:

- 1. DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PIN 1 CONFIGURATION MAY VARY.
- 4. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
- 5. DIMENSION TO BE DETERMINED AT SEATING PLANE C.
- 6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08MM AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT BE LESS THAN 0.07MM.
- 7. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25MM PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSION INCLUDING MOLD MISMATCH.
- 8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
- 9. HATCHED AREA TO BE KEEP OUT ZONE FOR PCB ROUTING.

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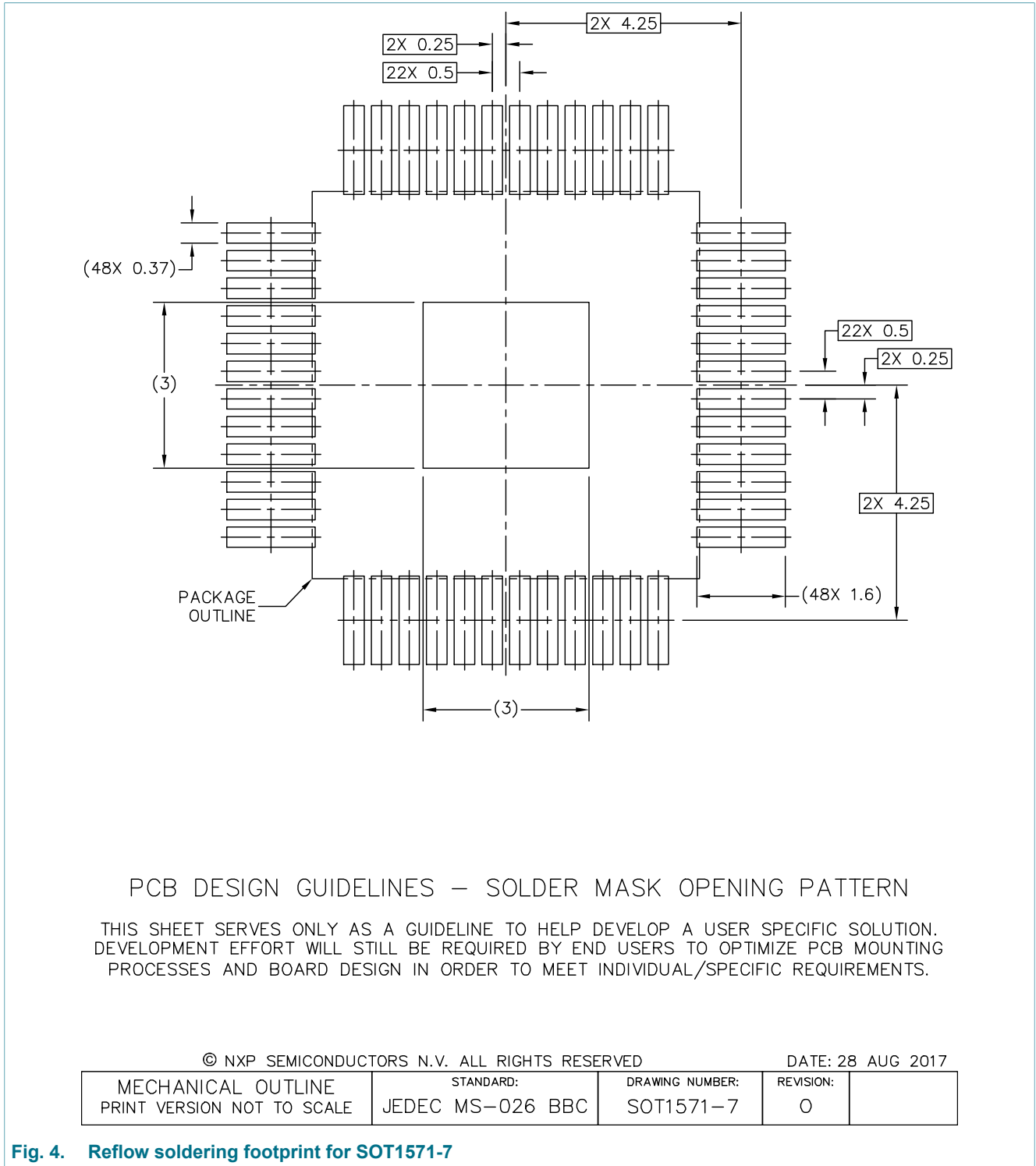
DATE: 28 AUG 2017

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: JEDEC MS-026 BBC	DRAWING NUMBER: SOT1571-7	REVISION: 0	
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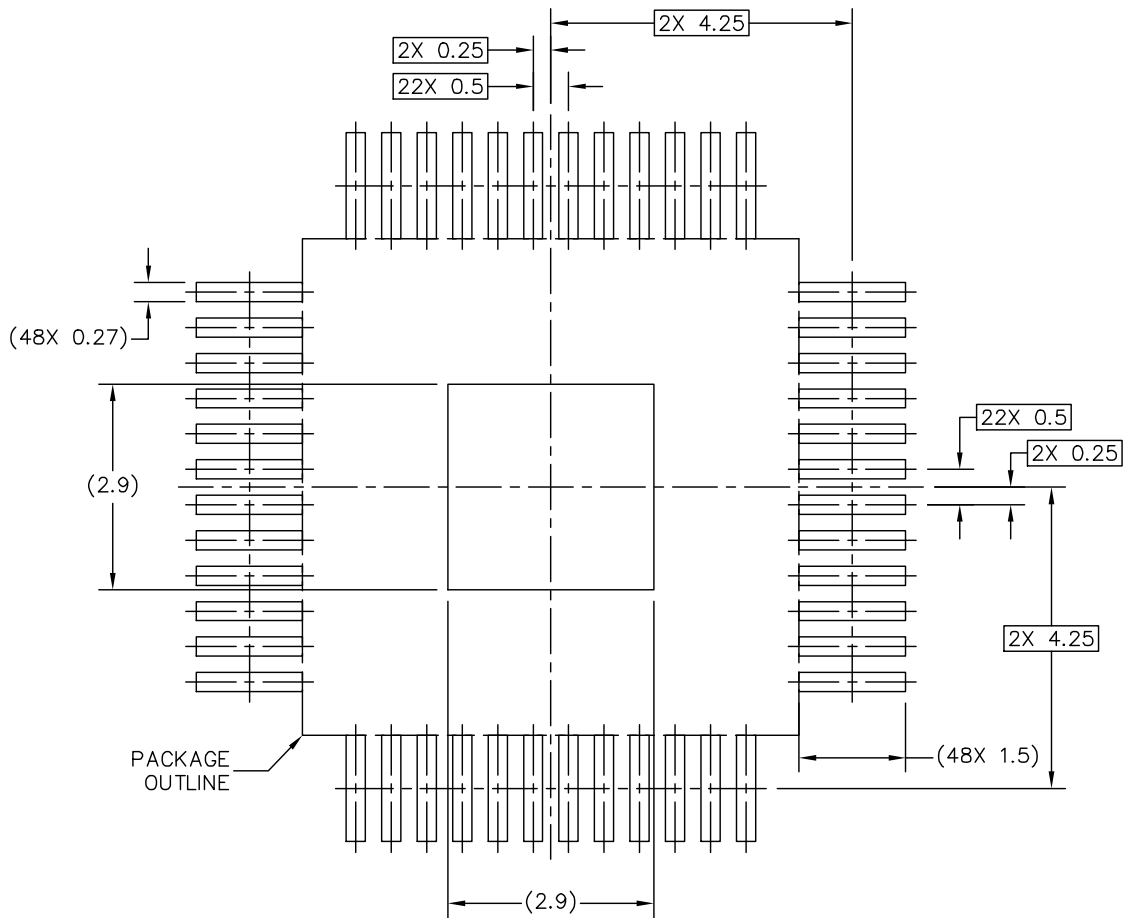
Fig. 3. Package outline note HLQFP48 (SOT1571-7)

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3. Soldering



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PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

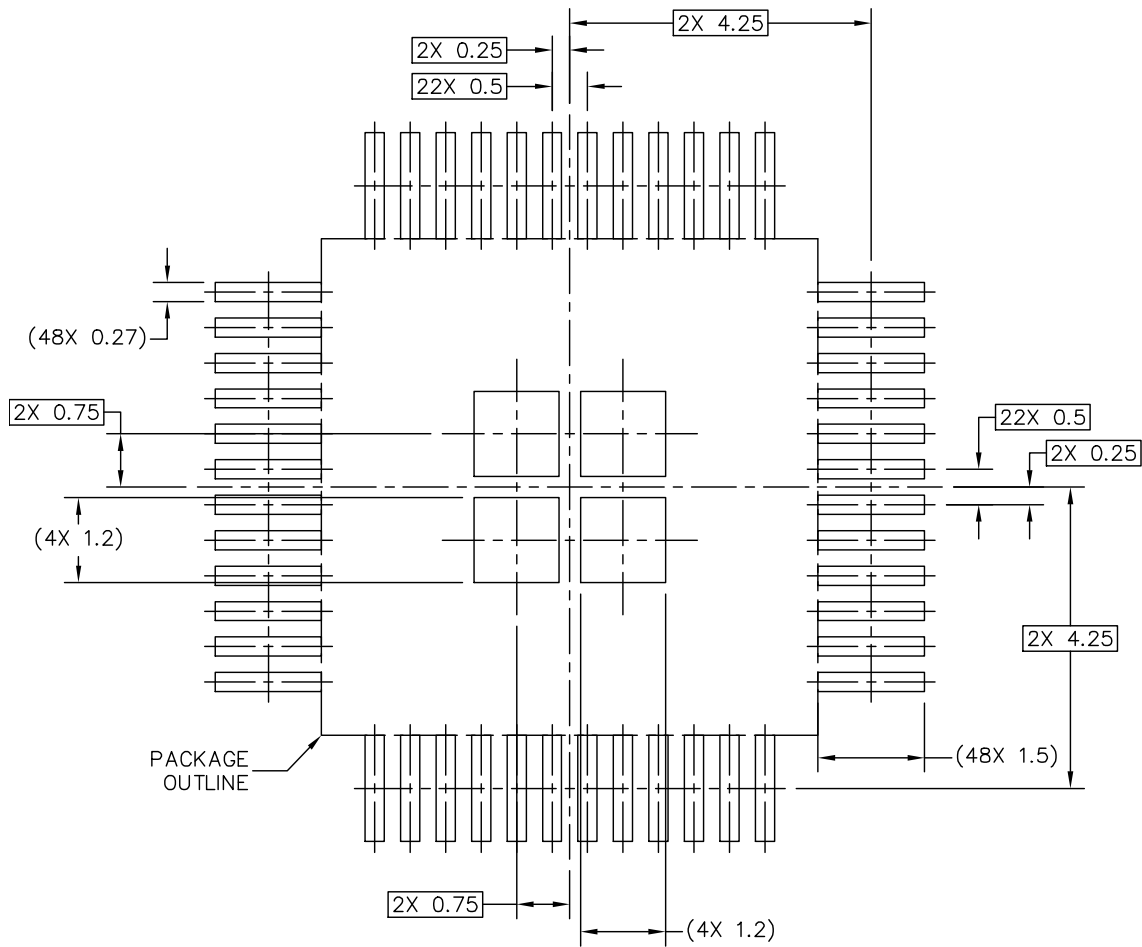
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Fig. 5. Reflow soldering footprint part2 for HLQFP48 (SOT1571-7)

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RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Fig. 6. Reflow soldering footprint part3 for HLQFP48 (SOT1571-7)

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body

4. Legal information

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